

C1812X103JATACTU

Aliases (C1812X103JATAC7800) SMD Comm X8G HT150C Flex, Ceramic, 0.01 uF, 5%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1812, 2.3 mm



Click here for the 3D model.

General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	67 mg
Shelf Life	78 Weeks
MSL	1

sions		Specifications
ze	1812	Capacitance
	4.5mm +/-0.4mm	Measurement Co
	3.2mm +/-0.3mm	Tolerance
	1mm +/-0.10mm	Voltage DC
	2.3mm MIN	Dielectric Withsta
	0.7mm +/-0.35mm	Temperature Ran
		Temp. Coefficien
ing Specifications		a a

Packaging Specifications	
Packaging	T&R, 180m
Packaging Quantity	1000

Dimensi Chip Siz L W T S B

> T&R, 180mm, Plastic Tape 1000

Specifications	
Capacitance	0.01 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	5%
Voltage DC	250 VDC
Dielectric Withstanding Voltage	625 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1%1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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